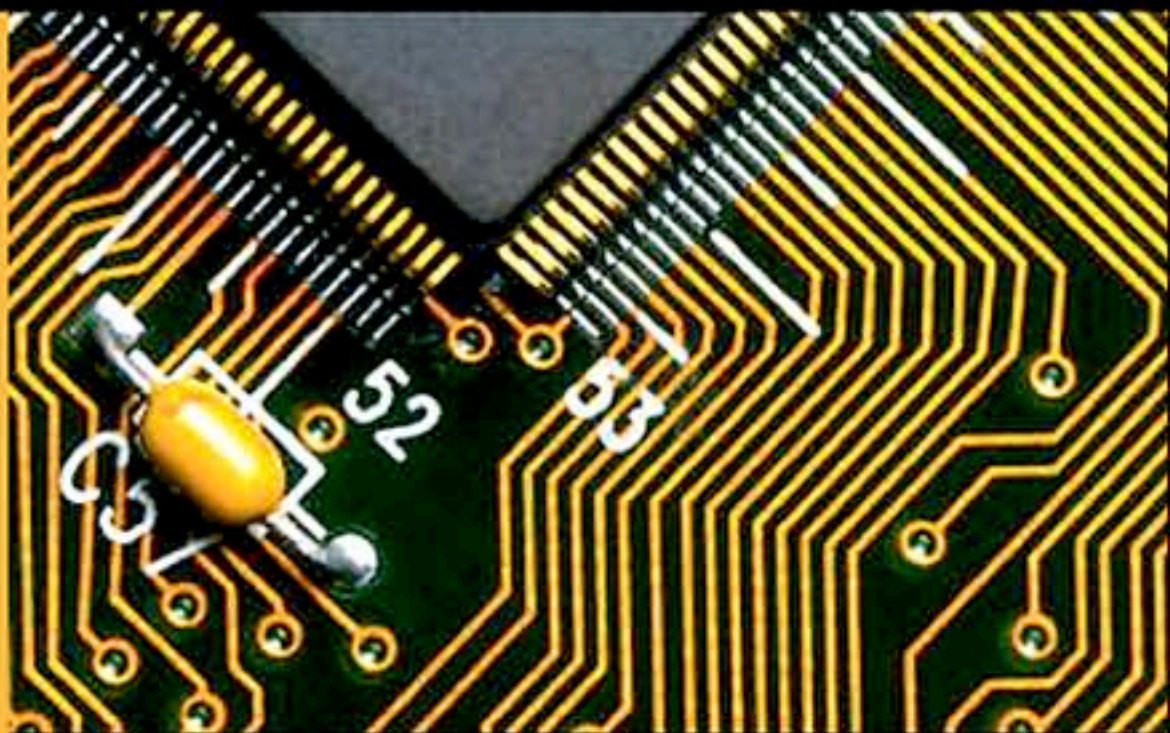


Second edition

The Circuit Designer's Companion



Tim Williams



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